

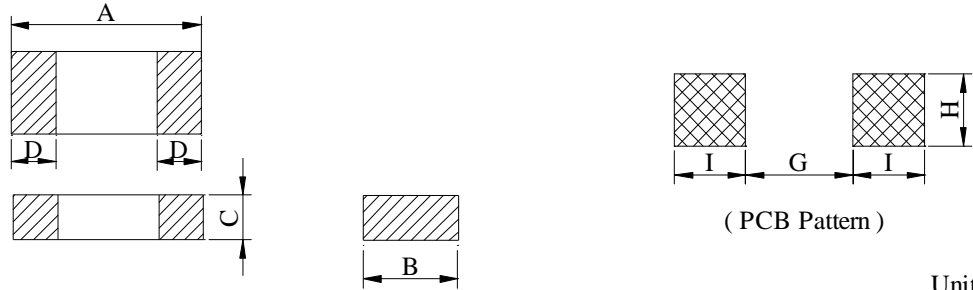
# SPECIFICATION FOR APPROVAL

REF : 20090527-A

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PROD. NAME	HIGH CURRENT MULTILAYER CHIP BEAD	ABC'S DWG NO.	MB□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

**I . CONFIGURATION & DIMENSIONS :**



Unit : m/m

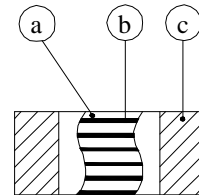
Series	A	B	C	D	G	H	I
MB4532	4.5±0.2	3.2±0.2	1.5±0.2	0.6±0.4	3.0	3.0	1.5
MB4516	4.5±0.2	1.6±0.2	1.6±0.2	0.6±0.4	3.0	1.4	1.5
MB3261	3.2±0.2	1.6±0.2	1.1±0.2	0.6±0.4	2.2	1.4	1.1
MB2029	2.0±0.2	1.2±0.2	0.9±0.2	0.5±0.3	1.0	1.0	1.0
MB1608	1.6±0.2	0.8±0.2	0.8±0.2	0.3±0.2	0.7	0.7	0.7

**II . SCHEMATIC DIAGRAM :**



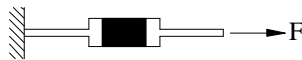
**III . MATERIALS :**

- a . Body : Ferrite
- b . Internal conductor : Silver or Ag / Pd
- c . Terminal : Ag/Ni/Sn
- d . Remark : Products comply with RoHS' requirements



**IV . GENERAL SPECIFICATION :**

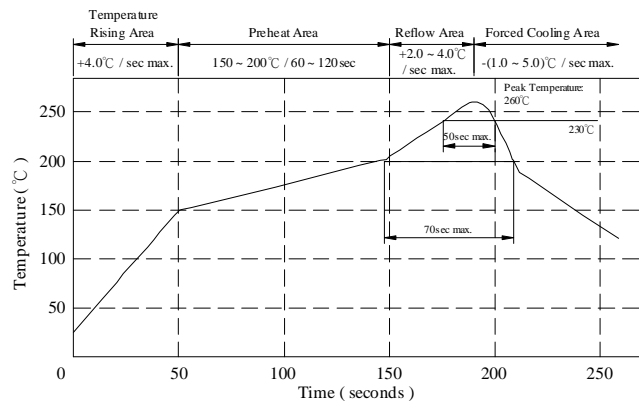
- a . Storage temp. : -40°C ---- +105°C
- b . Operating temp. : -55°C ---- +125°C
- c . Terminal strength :



Type	F ( kgf )	Time ( sec )
MB4532	1.5	
MB4516	1.0	
MB3261	1.0	30±5
MB2029	0.6	
MB1608	0.5	

- d . Solderability : Preheat : 150±25°C for 60 seconds  
 Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent  
 Solder temp. : 260±5°C  
 Flux : Rosin  
 Dip time : 4±1 seconds

Peak Temp : 260°C max.  
 Max time above 230°C : 50sec max.  
 Max time above 200°C : 70sec max.



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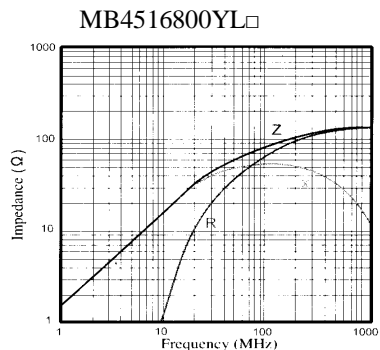
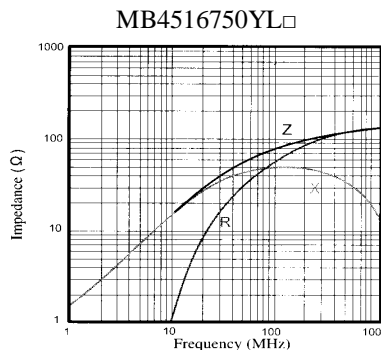
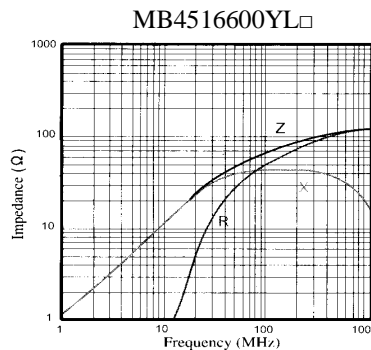
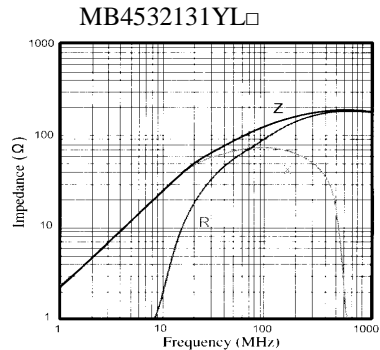
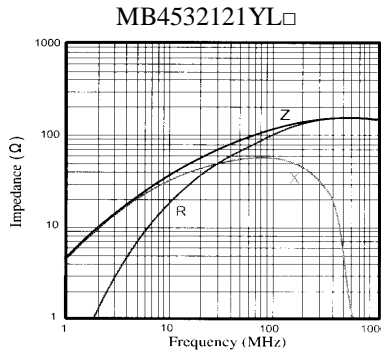
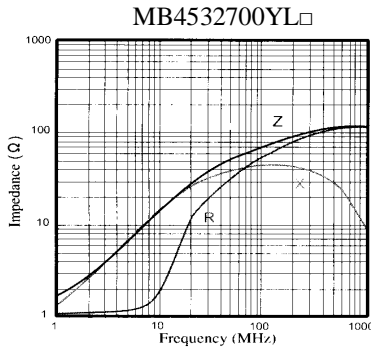
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PROD. NAME	HIGH CURRENT MULTILAYER CHIP BEAD	ABC'S DWG NO.	MB□□□□□□□□L□-□□□
		ABC'S ITEM NO.	

## V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance ( $\Omega$ ) at 100MHz	RDC (m $\Omega$ ) max.	IDC (A) max.
MB4532700YL□ -□□□	70±25%	30	6.0
MB4532121YL□ -□□□	120±25%	50	3.0
MB4532131YL□ -□□□	125±25%	50	3.0
MB4516600YL□ -□□□	60±25%	10	6.0
MB4516750YL□ -□□□	75±25%	25	3.0
MB4516800YL□ -□□□	80±25%	50	3.0

- 1). □ : Paclaging Information... **A** : Bulk **B** : Taping Reel  
 2). "- □□□ " : Reference code



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# SPECIFICATION FOR APPROVAL

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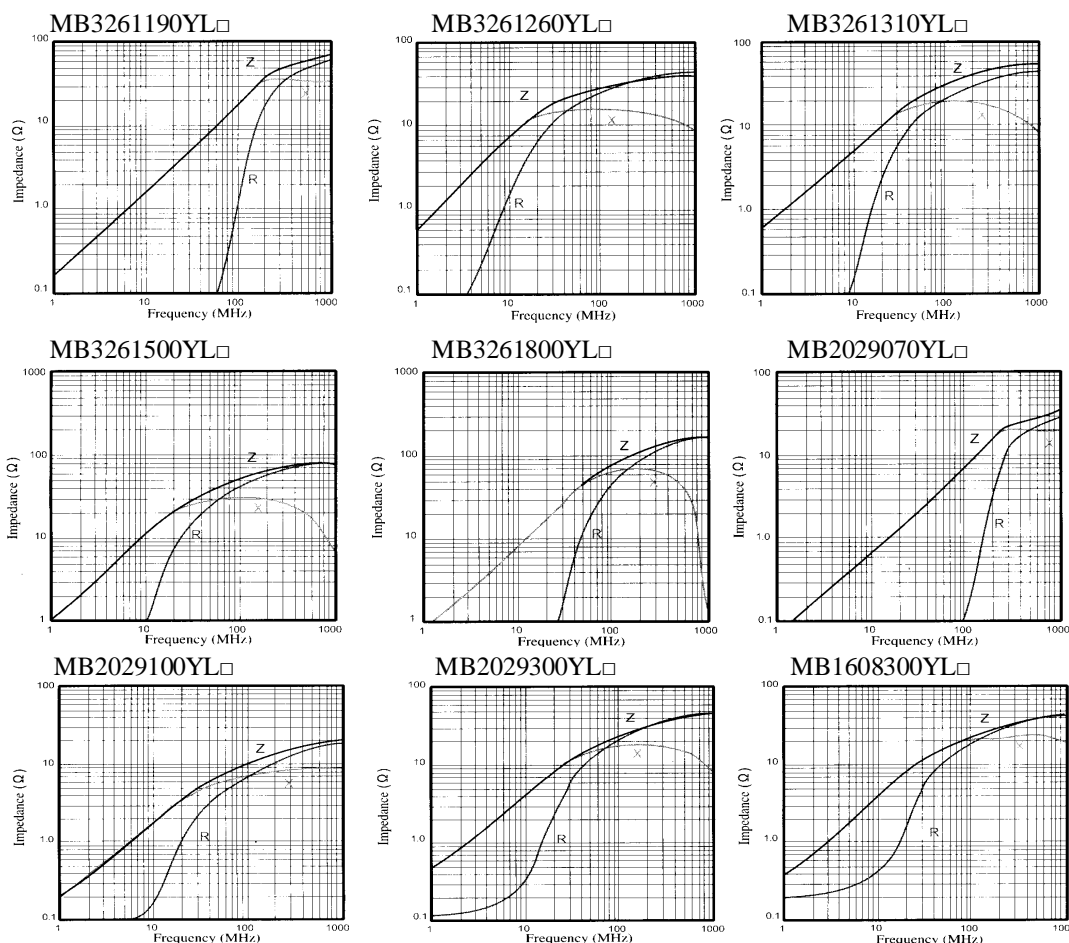
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PROD. NAME	HIGH CURRENT MULTILAYER CHIP BEAD	ABC'S DWG NO.  ABC'S ITEM NO.	MB□□□□□□□□L□-□□□
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## V . ELECTRICAL CHARACTERISTICS :

DWG No.	Impedance ( $\Omega$ ) at 100MHz	RDC (m $\Omega$ ) max.	IDC (A) max.
MB3261190YL□ -□□□	19±25%	40	3.0
MB3261260YL□ -□□□	26±25%	40	3.0
MB3261310YL□ -□□□	31±25%	40	3.0
MB3261500YL□ -□□□	50±25%	25	3.0
MB3261800YL□ -□□□	80±25%	30	3.0
MB2029070YL□ -□□□	7±25%	30	3.0
MB2029100YL□ -□□□	10±25%	30	3.0
MB2029300YL□ -□□□	30±25%	25	3.0
MB1608300YL□ -□□□	30±25%	60	1.0

- 1). □ : Paclaging Information... [A] : Bulk [B] : Taping Reel  
 2). "- □□□":Reference code



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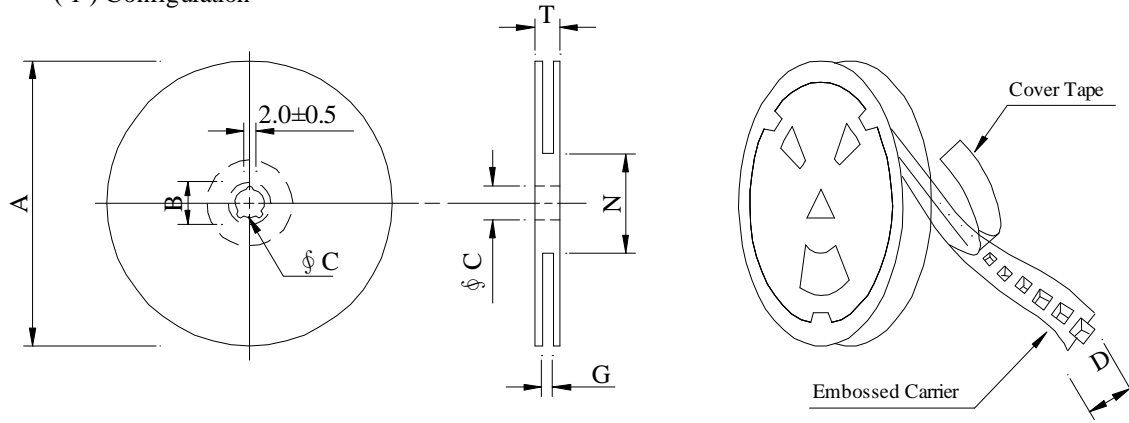
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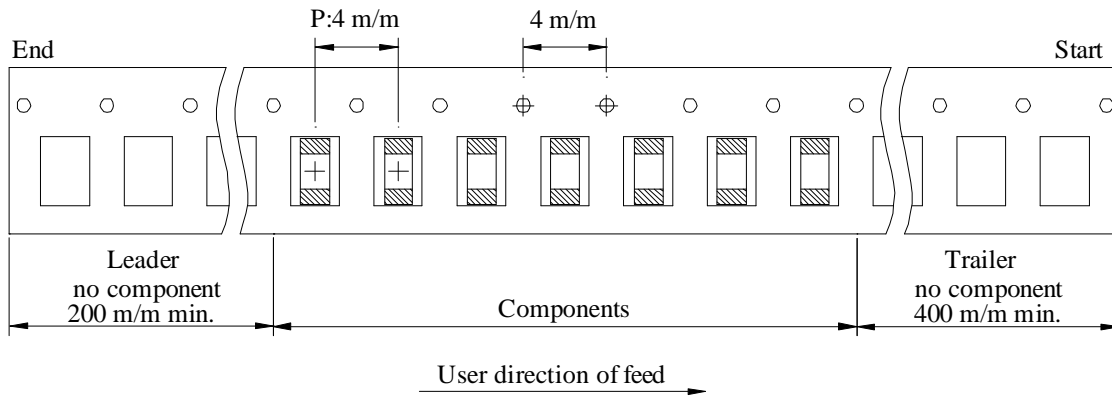
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		ABC'S ITEM NO.	

## VI . PACKAGING INFORMATION :

### (1) Configuration



※Carrier tape width : D



### (2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 <sup>+0</sup>	50 <sup>-0</sup>	12.5
07 - 12	178	21±0.8	13	12	14 <sup>+0</sup>	50 <sup>-0</sup>	16.5

### (3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY(kpcs)	G.W. (Kg)	Size (cm)
MB4532	1,000	170	07 - 12	30	9.3	41 x 39 x 22
MB4516	2,000	180	07 - 12	80	9.7	41 x 39 x 22
MB3261	3,000	150	07 - 08	120	8.5	41 x 39 x 22
MB2029	4,000	120	07 - 08	200	8.5	41 x 39 x 22
MB1608	4,000	90	07 - 08	200	7.0	41 x 39 x 22

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( 4 ) TYPE DIMENSIONS

Fig 1.

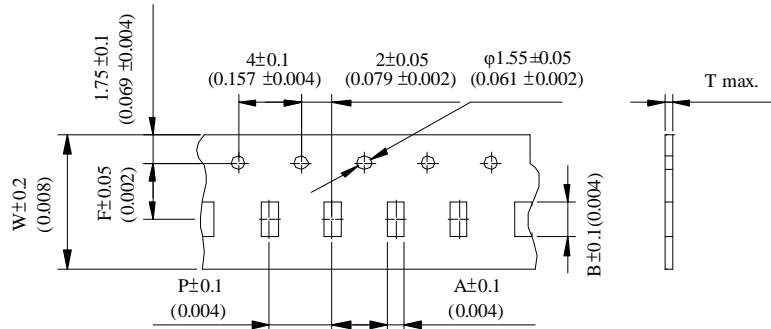
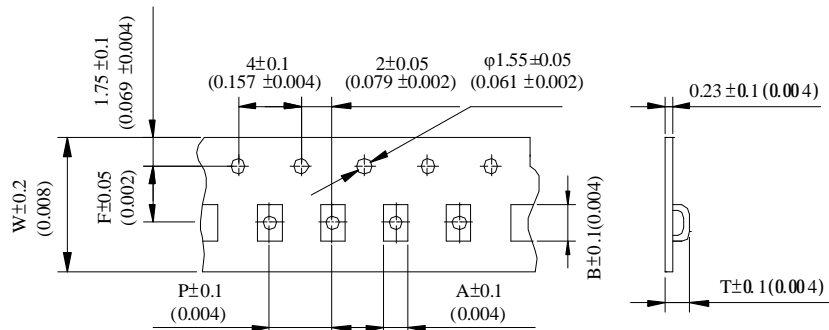


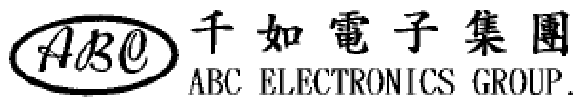
Fig 2.



Unit:m/m

Type	A	B	F	P	T	W	Fig
MB4532	3.66	4.95	5.50	8.0	1.85	12.0	2
MB4516	1.93	4.95	5.50	4.0	1.93	12.0	2
MB3261	1.88	3.50	3.50	4.0	1.27	8.0	2
MB2029	1.50	2.30	3.50	4.0	1.10	8.0	1
MB1608	1.05	1.85	3.50	4.0	1.10	8.0	1

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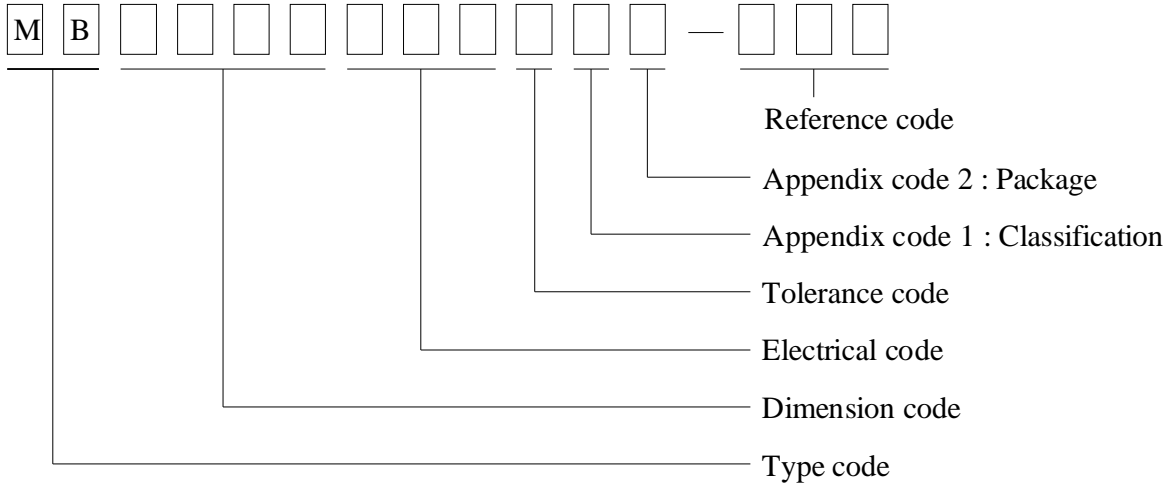
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		ABC'S ITEM NO.	

**VII . DWGING NUMBER EXPRESSION :**



**Appendix code 1 : Product Classification**

- L : Lead Free Standard products comply with RoHS' requirements
- 1 ~ 9 : Lead Free Special products comply with RoHS' requirements

**Appendix code 2 : Package Information**

Code	Inner package	Inner package QTY	Remark
A	T.B.D.	T.B.D.	
B	T / R ( Reel package )	1000 pcs	MB4532
	T / R ( Reel package )	2000 pcs	MB4516
	T / R ( Reel package )	3000 pcs	MB3261
	T / R ( Reel package )	4000 pcs	MB2029
	T / R ( Reel package )	4000 pcs	MB1608